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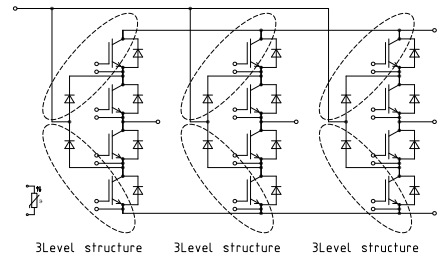
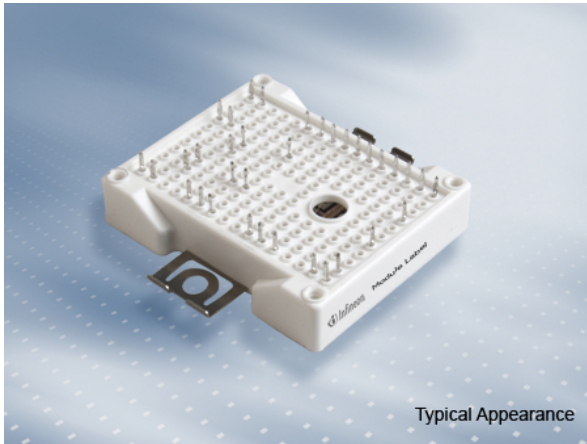
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EasyPACK Modul mit schnellem Trench/Feldstopp High-Speed 3 IGBT und SiC Diode und PressFIT / NTC  
 EasyPACK module with fast Trench/Fieldstop High-Speed 3 IGBT and SiC diode and PressFIT / NTC



$V_{CES} = 650V$   
 $I_{C\ nom} = 30A / I_{CRM} = 60A$

### Typische Anwendungen

- 3-Level-Applikationen
- Motorantriebe
- Solar Anwendungen
- USV-Systeme

### Elektrische Eigenschaften

- CoolSiC (TM) Schottky Diode Gen 5
- High Speed IGBT H3
- Niedrige Schaltverluste

### Mechanische Eigenschaften

- 3 kV AC 1min Isolationsfestigkeit
- Al<sub>2</sub>O<sub>3</sub> Substrat mit kleinem thermischen Widerstand
- Kompaktes Design
- PressFIT Verbindungstechnik
- Robuste Montage durch integrierte Befestigungsklammern

### Typical Applications

- 3-level-applications
- Motor drives
- Solar applications
- UPS systems

### Electrical Features

- CoolSiC (TM) Schottky diode gen 5
- High speed IGBT H3
- Low switching losses

### Mechanical Features

- 3 kV AC 1min insulation
- Al<sub>2</sub>O<sub>3</sub> substrate with low thermal resistance
- Compact design
- PressFIT contact technology
- Rugged mounting due to integrated mounting clamps

## Module Label Code

Barcode Code 128



DMX - Code



### Content of the Code

Content of the Code	Digit
Module Serial Number	1 - 5
Module Material Number	6 - 11
Production Order Number	12 - 19
Datecode (Production Year)	20 - 21
Datecode (Production Week)	22 - 23

## IGBT, Wechselrichter / IGBT, Inverter

### Höchstzulässige Werte / Maximum Rated Values

Kollektor-Emitter-Sperrspannung Collector-emitter voltage	$T_{vj} = 25^{\circ}\text{C}$	$V_{CES}$	650	V
Kollektor-Dauergleichstrom Continuous DC collector current	$T_H = 25^{\circ}\text{C}, T_{vj\max} = 175^{\circ}\text{C}$	$I_{C\text{nom}}$	30	A
Periodischer Kollektor-Spitzenstrom Repetitive peak collector current	$t_P = 1\text{ ms}$	$I_{CRM}$	60	A
Gate-Emitter-Spitzenspannung Gate-emitter peak voltage		$V_{GES}$	+/-20	V

### Charakteristische Werte / Characteristic Values

			min.	typ.	max.		
Kollektor-Emitter-Sättigungsspannung Collector-emitter saturation voltage	$I_C = 30\text{ A}, V_{GE} = 15\text{ V}$ $I_C = 30\text{ A}, V_{GE} = 15\text{ V}$ $I_C = 30\text{ A}, V_{GE} = 15\text{ V}$	$T_{vj} = 25^{\circ}\text{C}$ $T_{vj} = 125^{\circ}\text{C}$ $T_{vj} = 150^{\circ}\text{C}$	$V_{CE\text{sat}}$	1,50 1,70 1,80	1,90	V V V	
Gate-Schwellenspannung Gate threshold voltage	$I_C = 0,80\text{ mA}, V_{CE} = V_{GE}, T_{vj} = 25^{\circ}\text{C}$		$V_{GEth}$	5,00	5,80	6,50	V
Gateladung Gate charge	$V_{GE} = -15\text{ V} \dots +15\text{ V}$		$Q_G$	0,30			$\mu\text{C}$
Interner Gatewiderstand Internal gate resistor	$T_{vj} = 25^{\circ}\text{C}$		$R_{Gint}$	0,0			$\Omega$
Eingangskapazität Input capacitance	$f = 1\text{ MHz}, T_{vj} = 25^{\circ}\text{C}, V_{CE} = 25\text{ V}, V_{GE} = 0\text{ V}$		$C_{ies}$	1,65			nF
Rückwirkungskapazität Reverse transfer capacitance	$f = 1\text{ MHz}, T_{vj} = 25^{\circ}\text{C}, V_{CE} = 25\text{ V}, V_{GE} = 0\text{ V}$		$C_{res}$	0,051			nF
Kollektor-Emitter-Reststrom Collector-emitter cut-off current	$V_{CE} = 650\text{ V}, V_{GE} = 0\text{ V}, T_{vj} = 25^{\circ}\text{C}$		$I_{CES}$			1,0	mA
Gate-Emitter-Reststrom Gate-emitter leakage current	$V_{CE} = 0\text{ V}, V_{GE} = 20\text{ V}, T_{vj} = 25^{\circ}\text{C}$		$I_{GES}$			100	nA
Einschaltverzögerungszeit, induktive Last Turn-on delay time, inductive load	$I_C = 30\text{ A}, V_{CE} = 300\text{ V}$ $V_{GE} = \pm 15\text{ V}$ $R_{Gon} = 33\ \Omega$	$T_{vj} = 25^{\circ}\text{C}$ $T_{vj} = 125^{\circ}\text{C}$ $T_{vj} = 150^{\circ}\text{C}$	$t_{don}$	0,042 0,044 0,044			$\mu\text{s}$ $\mu\text{s}$ $\mu\text{s}$
Anstiegszeit, induktive Last Rise time, inductive load	$I_C = 30\text{ A}, V_{CE} = 300\text{ V}$ $V_{GE} = \pm 15\text{ V}$ $R_{Gon} = 33\ \Omega$	$T_{vj} = 25^{\circ}\text{C}$ $T_{vj} = 125^{\circ}\text{C}$ $T_{vj} = 150^{\circ}\text{C}$	$t_r$	0,038 0,044 0,044			$\mu\text{s}$ $\mu\text{s}$ $\mu\text{s}$
Abschaltverzögerungszeit, induktive Last Turn-off delay time, inductive load	$I_C = 30\text{ A}, V_{CE} = 300\text{ V}$ $V_{GE} = \pm 15\text{ V}$ $R_{Goff} = 33\ \Omega$	$T_{vj} = 25^{\circ}\text{C}$ $T_{vj} = 125^{\circ}\text{C}$ $T_{vj} = 150^{\circ}\text{C}$	$t_{doff}$	0,26 0,28 0,285			$\mu\text{s}$ $\mu\text{s}$ $\mu\text{s}$
Fallzeit, induktive Last Fall time, inductive load	$I_C = 30\text{ A}, V_{CE} = 300\text{ V}$ $V_{GE} = \pm 15\text{ V}$ $R_{Goff} = 33\ \Omega$	$T_{vj} = 25^{\circ}\text{C}$ $T_{vj} = 125^{\circ}\text{C}$ $T_{vj} = 150^{\circ}\text{C}$	$t_f$	0,042 0,06 0,065			$\mu\text{s}$ $\mu\text{s}$ $\mu\text{s}$
Einschaltverlustenergie pro Puls Turn-on energy loss per pulse	$I_C = 30\text{ A}, V_{CE} = 300\text{ V}, L_S = 35\text{ nH}$ $V_{GE} = \pm 15\text{ V}, di/dt = 800\text{ A}/\mu\text{s} (T_{vj} = 150^{\circ}\text{C})$ $R_{Gon} = 33\ \Omega$	$T_{vj} = 25^{\circ}\text{C}$ $T_{vj} = 125^{\circ}\text{C}$ $T_{vj} = 150^{\circ}\text{C}$	$E_{on}$	0,88 1,10 1,15			mJ mJ mJ
Abschaltverlustenergie pro Puls Turn-off energy loss per pulse	$I_C = 30\text{ A}, V_{CE} = 300\text{ V}, L_S = 35\text{ nH}$ $V_{GE} = \pm 15\text{ V}, du/dt = 3700\text{ V}/\mu\text{s} (T_{vj} = 150^{\circ}\text{C})$ $R_{Goff} = 33\ \Omega$	$T_{vj} = 25^{\circ}\text{C}$ $T_{vj} = 125^{\circ}\text{C}$ $T_{vj} = 150^{\circ}\text{C}$	$E_{off}$	0,67 0,84 0,91			mJ mJ mJ
Kurzschlußverhalten SC data	$V_{GE} \leq 15\text{ V}, V_{CC} = 360\text{ V}$ $V_{CEmax} = V_{CES} - L_{SCE} \cdot di/dt$	$t_P \leq 6\ \mu\text{s}, T_{vj} = 150^{\circ}\text{C}$	$I_{SC}$	160			A
Wärmewiderstand, Chip bis Kühlkörper Thermal resistance, junction to heatsink	pro IGBT / per IGBT		$R_{thJH}$	2,15			K/W
Temperatur im Schaltbetrieb Temperature under switching conditions			$T_{vj\text{op}}$	-40	150		$^{\circ}\text{C}$

## Diode, Wechselrichter / Diode, Inverter

### Höchstzulässige Werte / Maximum Rated Values

Periodische Spitzensperrspannung Repetitive peak reverse voltage	$T_{vj} = 25^{\circ}\text{C}$	$V_{RRM}$	650	V
Dauergleichstrom Continuous DC forward current		$I_F$	30	A
Periodischer Spitzenstrom Repetitive peak forward current	$t_P = 1\text{ ms}$	$I_{FRM}$	60	A
Grenzlastintegral $I^2t$ - value	$V_R = 0\text{ V}, t_P = 10\text{ ms}, T_{vj} = 125^{\circ}\text{C}$ $V_R = 0\text{ V}, t_P = 10\text{ ms}, T_{vj} = 150^{\circ}\text{C}$	$I^2t$	90,0 82,0	$\text{A}^2\text{s}$ $\text{A}^2\text{s}$

### Charakteristische Werte / Characteristic Values

			min.	typ.	max.	
Durchlassspannung Forward voltage	$I_F = 30\text{ A}, V_{GE} = 0\text{ V}$	$T_{vj} = 25^{\circ}\text{C}$		1,60	2,00	V
	$I_F = 30\text{ A}, V_{GE} = 0\text{ V}$	$T_{vj} = 125^{\circ}\text{C}$	$V_F$	1,55		V
	$I_F = 30\text{ A}, V_{GE} = 0\text{ V}$	$T_{vj} = 150^{\circ}\text{C}$		1,50		V
Rückstromspitze Peak reverse recovery current	$I_F = 30\text{ A}, -di_F/dt = 800\text{ A}/\mu\text{s} (T_{vj}=150^{\circ}\text{C})$	$T_{vj} = 25^{\circ}\text{C}$		15,5		A
	$V_R = 300\text{ V}$	$T_{vj} = 125^{\circ}\text{C}$	$I_{RM}$	20,5		A
	$V_{GE} = -15\text{ V}$	$T_{vj} = 150^{\circ}\text{C}$		22,0		A
Sperrverzögerungsladung Recovered charge	$I_F = 30\text{ A}, -di_F/dt = 800\text{ A}/\mu\text{s} (T_{vj}=150^{\circ}\text{C})$	$T_{vj} = 25^{\circ}\text{C}$		1,10		$\mu\text{C}$
	$V_R = 300\text{ V}$	$T_{vj} = 125^{\circ}\text{C}$	$Q_r$	1,90		$\mu\text{C}$
	$V_{GE} = -15\text{ V}$	$T_{vj} = 150^{\circ}\text{C}$		2,20		$\mu\text{C}$
Abschaltenergie pro Puls Reverse recovery energy	$I_F = 30\text{ A}, -di_F/dt = 800\text{ A}/\mu\text{s} (T_{vj}=150^{\circ}\text{C})$	$T_{vj} = 25^{\circ}\text{C}$		0,18		mJ
	$V_R = 300\text{ V}$	$T_{vj} = 125^{\circ}\text{C}$	$E_{rec}$	0,34		mJ
	$V_{GE} = -15\text{ V}$	$T_{vj} = 150^{\circ}\text{C}$		0,41		mJ
Wärmewiderstand, Chip bis Kühlkörper Thermal resistance, junction to heatsink	pro Diode / per diode	$R_{thJH}$		2,60		K/W
Temperatur im Schaltbetrieb Temperature under switching conditions		$T_{vj\text{ op}}$	-40		150	$^{\circ}\text{C}$

## IGBT,3-Level / IGBT,3-Level

### Höchstzulässige Werte / Maximum Rated Values

Kollektor-Emitter-Sperrspannung Collector-emitter voltage	$T_{vj} = 25^{\circ}\text{C}$	$V_{CES}$	650	V
Kollektor-Dauergleichstrom Continuous DC collector current	$T_H = 25^{\circ}\text{C}, T_{vj\text{ max}} = 175^{\circ}\text{C}$	$I_{C\text{ nom}}$	30	A
Periodischer Kollektor-Spitzenstrom Repetitive peak collector current	$t_P = 1\text{ ms}$	$I_{CRM}$	60	A
Gate-Emitter-Spitzenspannung Gate-emitter peak voltage		$V_{GES}$	+/-20	V

### Charakteristische Werte / Characteristic Values

			min.	typ.	max.	
Kollektor-Emitter-Sättigungsspannung Collector-emitter saturation voltage	$I_C = 30\text{ A}, V_{GE} = 15\text{ V}$ $I_C = 30\text{ A}, V_{GE} = 15\text{ V}$ $I_C = 30\text{ A}, V_{GE} = 15\text{ V}$	$T_{vj} = 25^{\circ}\text{C}$ $T_{vj} = 125^{\circ}\text{C}$ $T_{vj} = 150^{\circ}\text{C}$	$V_{CE\text{ sat}}$	1,55 1,80 1,85	1,95	V V V
Gate-Schwellenspannung Gate threshold voltage	$I_C = 0,80\text{ mA}, V_{CE} = V_{GE}, T_{vj} = 25^{\circ}\text{C}$		$V_{GEth}$	5,00 5,80	6,50	V
Gateladung Gate charge	$V_{GE} = -15\text{ V} \dots +15\text{ V}$		$Q_G$	0,30		$\mu\text{C}$
Interner Gatewiderstand Internal gate resistor	$T_{vj} = 25^{\circ}\text{C}$		$R_{Gint}$	0,0		$\Omega$
Eingangskapazität Input capacitance	$f = 1\text{ MHz}, T_{vj} = 25^{\circ}\text{C}, V_{CE} = 25\text{ V}, V_{GE} = 0\text{ V}$		$C_{ies}$	1,65		nF
Rückwirkungskapazität Reverse transfer capacitance	$f = 1\text{ MHz}, T_{vj} = 25^{\circ}\text{C}, V_{CE} = 25\text{ V}, V_{GE} = 0\text{ V}$		$C_{res}$	0,051		nF
Kollektor-Emitter-Reststrom Collector-emitter cut-off current	$V_{CE} = 650\text{ V}, V_{GE} = 0\text{ V}, T_{vj} = 25^{\circ}\text{C}$		$I_{CES}$		1,0	mA
Gate-Emitter-Reststrom Gate-emitter leakage current	$V_{CE} = 0\text{ V}, V_{GE} = 20\text{ V}, T_{vj} = 25^{\circ}\text{C}$		$I_{GES}$		100	nA
Einschaltverzögerungszeit, induktive Last Turn-on delay time, inductive load	$I_C = 30\text{ A}, V_{CE} = 300\text{ V}$ $V_{GE} = \pm 15\text{ V}$ $R_{Gon} = 20\ \Omega$	$T_{vj} = 25^{\circ}\text{C}$ $T_{vj} = 125^{\circ}\text{C}$ $T_{vj} = 150^{\circ}\text{C}$	$t_{don}$	0,03 0,03 0,031		$\mu\text{s}$ $\mu\text{s}$ $\mu\text{s}$
Anstiegszeit, induktive Last Rise time, inductive load	$I_C = 30\text{ A}, V_{CE} = 300\text{ V}$ $V_{GE} = \pm 15\text{ V}$ $R_{Gon} = 20\ \Omega$	$T_{vj} = 25^{\circ}\text{C}$ $T_{vj} = 125^{\circ}\text{C}$ $T_{vj} = 150^{\circ}\text{C}$	$t_r$	0,035 0,036 0,05		$\mu\text{s}$ $\mu\text{s}$ $\mu\text{s}$
Abschaltverzögerungszeit, induktive Last Turn-off delay time, inductive load	$I_C = 30\text{ A}, V_{CE} = 300\text{ V}$ $V_{GE} = \pm 15\text{ V}$ $R_{Goff} = 20\ \Omega$	$T_{vj} = 25^{\circ}\text{C}$ $T_{vj} = 125^{\circ}\text{C}$ $T_{vj} = 150^{\circ}\text{C}$	$t_{doff}$	0,175 0,19 0,20		$\mu\text{s}$ $\mu\text{s}$ $\mu\text{s}$
Fallzeit, induktive Last Fall time, inductive load	$I_C = 30\text{ A}, V_{CE} = 300\text{ V}$ $V_{GE} = \pm 15\text{ V}$ $R_{Goff} = 20\ \Omega$	$T_{vj} = 25^{\circ}\text{C}$ $T_{vj} = 125^{\circ}\text{C}$ $T_{vj} = 150^{\circ}\text{C}$	$t_f$	0,019 0,038 0,043		$\mu\text{s}$ $\mu\text{s}$ $\mu\text{s}$
Einschaltverlustenergie pro Puls Turn-on energy loss per pulse	$I_C = 30\text{ A}, V_{CE} = 300\text{ V}, L_S = 35\text{ nH}$ $V_{GE} = \pm 15\text{ V}, di/dt = 830\text{ A}/\mu\text{s} (T_{vj} = 150^{\circ}\text{C})$ $R_{Gon} = 20\ \Omega$	$T_{vj} = 25^{\circ}\text{C}$ $T_{vj} = 125^{\circ}\text{C}$ $T_{vj} = 150^{\circ}\text{C}$	$E_{on}$	0,38 0,40 0,41		mJ mJ mJ
Abschaltverlustenergie pro Puls Turn-off energy loss per pulse	$I_C = 30\text{ A}, V_{CE} = 300\text{ V}, L_S = 35\text{ nH}$ $V_{GE} = \pm 15\text{ V}, du/dt = 5400\text{ V}/\mu\text{s} (T_{vj} = 150^{\circ}\text{C})$ $R_{Goff} = 20\ \Omega$	$T_{vj} = 25^{\circ}\text{C}$ $T_{vj} = 125^{\circ}\text{C}$ $T_{vj} = 150^{\circ}\text{C}$	$E_{off}$	0,42 0,64 0,71		mJ mJ mJ
Kurzschlußverhalten SC data	$V_{GE} \leq 15\text{ V}, V_{CC} = 360\text{ V}$ $V_{CEmax} = V_{CES} - L_{SCE} \cdot di/dt$	$t_P \leq 5\ \mu\text{s}, T_{vj} = 150^{\circ}\text{C}$	$I_{SC}$	160		A
Wärmewiderstand, Chip bis Kühlkörper Thermal resistance, junction to heatsink	pro IGBT / per IGBT		$R_{thJH}$	2,15		K/W
Temperatur im Schaltbetrieb Temperature under switching conditions			$T_{vj\text{ op}}$	-40	150	$^{\circ}\text{C}$

## Diode, 3-Level / Diode, 3-Level

### Höchstzulässige Werte / Maximum Rated Values

Periodische Spitzensperrspannung Repetitive peak reverse voltage	$T_{vj} = 25^{\circ}\text{C}$	$V_{RRM}$	650	V
Dauergleichstrom Continuous DC forward current		$I_F$	10	A
Periodischer Spitzenstrom Repetitive peak forward current	$t_p = 1\text{ ms}$	$I_{FRM}$	20	A
Grenzlastintegral $I^2t$ - value	$V_R = 0\text{ V}, t_p = 10\text{ ms}, T_{vj} = 125^{\circ}\text{C}$	$I^2t$	4,50	A <sup>2</sup> s

### Charakteristische Werte / Characteristic Values

			min.	typ.	max.	
Durchlassspannung Forward voltage	$I_F = 10\text{ A}, V_{GE} = 0\text{ V}$ $I_F = 10\text{ A}, V_{GE} = 0\text{ V}$ $I_F = 10\text{ A}, V_{GE} = 0\text{ V}$	$T_{vj} = 25^{\circ}\text{C}$ $T_{vj} = 125^{\circ}\text{C}$ $T_{vj} = 150^{\circ}\text{C}$	$V_F$	1,45 1,60 1,65	1,85	V V V
Rückstromspitze Peak reverse recovery current	$I_F = 10\text{ A}, -di_F/dt = 400\text{ A}/\mu\text{s} (T_{vj}=150^{\circ}\text{C})$ $V_R = 300\text{ V}$ $V_{GE} = 15\text{ V}$	$T_{vj} = 25^{\circ}\text{C}$ $T_{vj} = 125^{\circ}\text{C}$ $T_{vj} = 150^{\circ}\text{C}$	$I_{RM}$	6,30 6,80 6,90		A A A
Sperrverzögerungsladung Recovered charge	$I_F = 10\text{ A}, -di_F/dt = 400\text{ A}/\mu\text{s} (T_{vj}=150^{\circ}\text{C})$ $V_R = 300\text{ V}$ $V_{GE} = 15\text{ V}$	$T_{vj} = 25^{\circ}\text{C}$ $T_{vj} = 125^{\circ}\text{C}$ $T_{vj} = 150^{\circ}\text{C}$	$Q_r$	0,22 0,37 0,40		$\mu\text{C}$ $\mu\text{C}$ $\mu\text{C}$
Abschaltenergie pro Puls Reverse recovery energy	$I_F = 10\text{ A}, -di_F/dt = 400\text{ A}/\mu\text{s} (T_{vj}=150^{\circ}\text{C})$ $V_R = 300\text{ V}$ $V_{GE} = 15\text{ V}$	$T_{vj} = 25^{\circ}\text{C}$ $T_{vj} = 125^{\circ}\text{C}$ $T_{vj} = 150^{\circ}\text{C}$	$E_{rec}$	0,01 0,01 0,01		mJ mJ mJ
Wärmewiderstand, Chip bis Kühlkörper Thermal resistance, junction to heatsink	pro Diode / per diode		$R_{thJH}$	3,92		K/W
Temperatur im Schaltbetrieb Temperature under switching conditions			$T_{vj\text{ op}}$	-40	150	$^{\circ}\text{C}$

## NTC-Widerstand / NTC-Thermistor

### Charakteristische Werte / Characteristic Values

			min.	typ.	max.	
Nennwiderstand Rated resistance	$T_{NTC} = 25^{\circ}\text{C}$		$R_{25}$	5,00		k $\Omega$
Abweichung von R100 Deviation of R100	$T_{NTC} = 100^{\circ}\text{C}, R_{100} = 493\ \Omega$		$\Delta R/R$	-5	5	%
Verlustleistung Power dissipation	$T_{NTC} = 25^{\circ}\text{C}$		$P_{25}$		20,0	mW
B-Wert B-value	$R_2 = R_{25} \exp [B_{25/50}(1/T_2 - 1/(298,15\text{ K}))]$		$B_{25/50}$	3375		K
B-Wert B-value	$R_2 = R_{25} \exp [B_{25/80}(1/T_2 - 1/(298,15\text{ K}))]$		$B_{25/80}$	3411		K
B-Wert B-value	$R_2 = R_{25} \exp [B_{25/100}(1/T_2 - 1/(298,15\text{ K}))]$		$B_{25/100}$	3433		K

Angaben gemäß gültiger Application Note.  
Specification according to the valid application note.

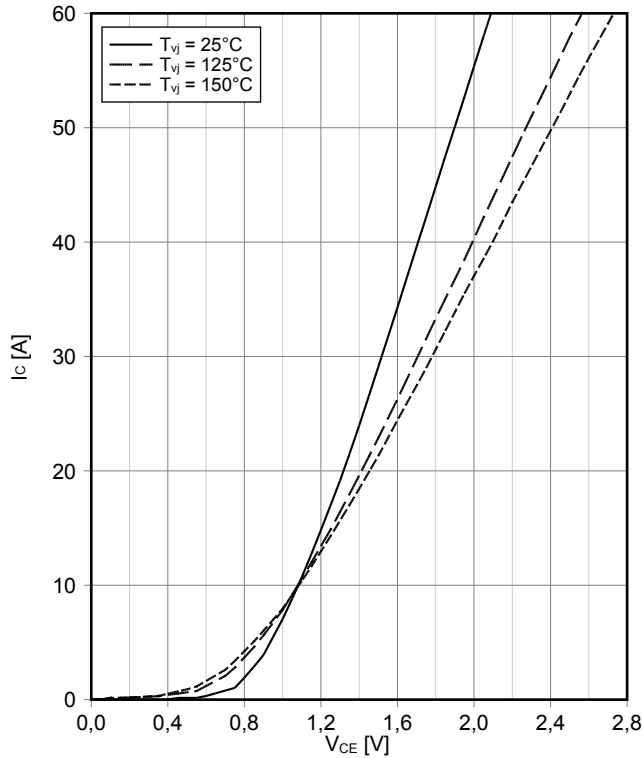
## Modul / Module

Isolations-Prüfspannung Isolation test voltage	RMS, f = 50 Hz, t = 1 min.	V <sub>ISOL</sub>	3,0			kV
Innere Isolation Internal isolation	Basisisolierung (Schutzklasse 1, EN61140) basic insulation (class 1, IEC 61140)		Al <sub>2</sub> O <sub>3</sub>			
Kriechstrecke Creepage distance	Kontakt - Kühlkörper / terminal to heatsink Kontakt - Kontakt / terminal to terminal		11,5 6,3			mm
Luftstrecke Clearance	Kontakt - Kühlkörper / terminal to heatsink Kontakt - Kontakt / terminal to terminal		10,0 5,0			mm
Vergleichszahl der Kriechwegbildung Comperative tracking index		CTI	> 200			
			min.	typ.	max.	
Modulstreuintuktivität Stray inductance module		L <sub>sCE</sub>		45		nH
Lagertemperatur Storage temperature		T <sub>stg</sub>	-40		125	°C
Anpresskraft für mech. Bef. pro Feder mounting force per clamp		F	40	-	80	N
Gewicht Weight		G		39		g

Der Strom im Dauerbetrieb ist auf 25A effektiv pro Anschlusspin begrenzt.  
The current under continuous operation is limited to 25A rms per connector pin

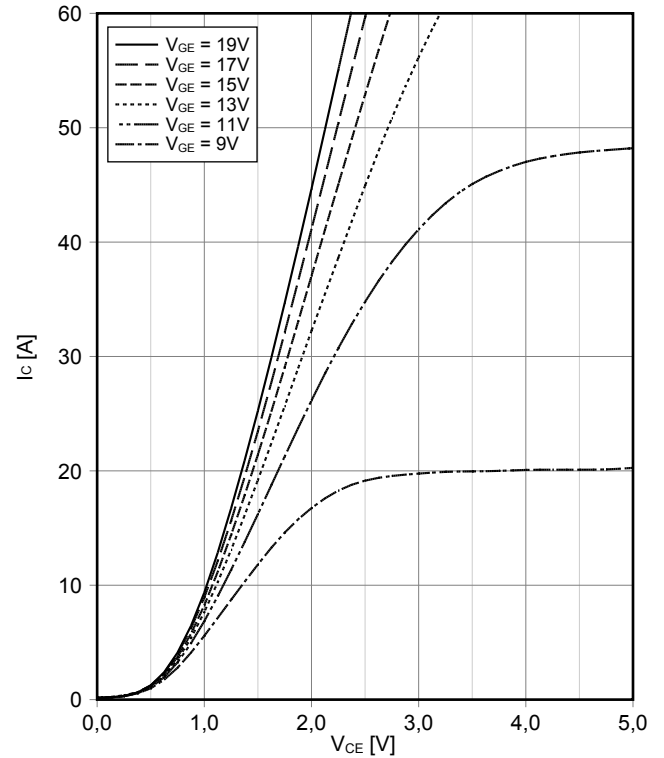
**Ausgangskennlinie IGBT, Wechselrichter (typisch)**  
**output characteristic IGBT, Inverter (typical)**

$I_C = f(V_{CE})$   
 $V_{GE} = 15\text{ V}$



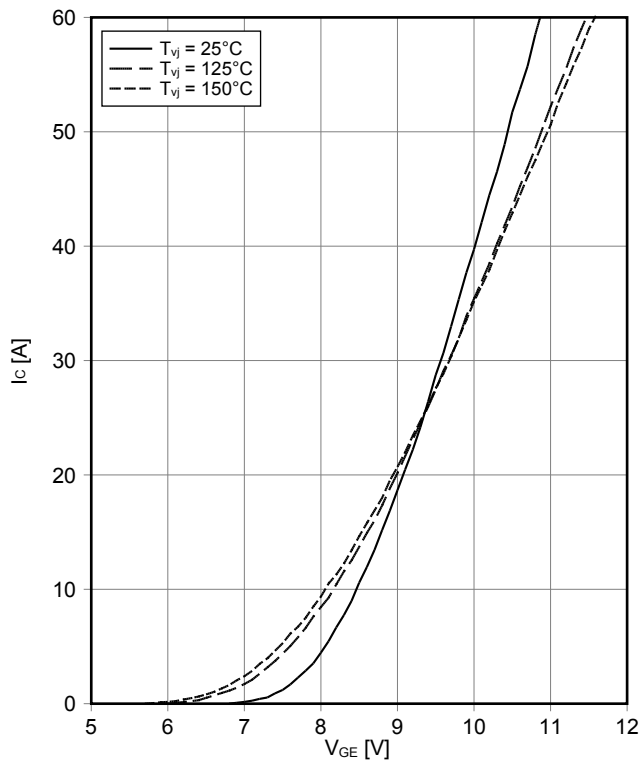
**Ausgangskennlinienfeld IGBT, Wechselrichter (typisch)**  
**output characteristic IGBT, Inverter (typical)**

$I_C = f(V_{CE})$   
 $T_{vj} = 150^\circ\text{C}$



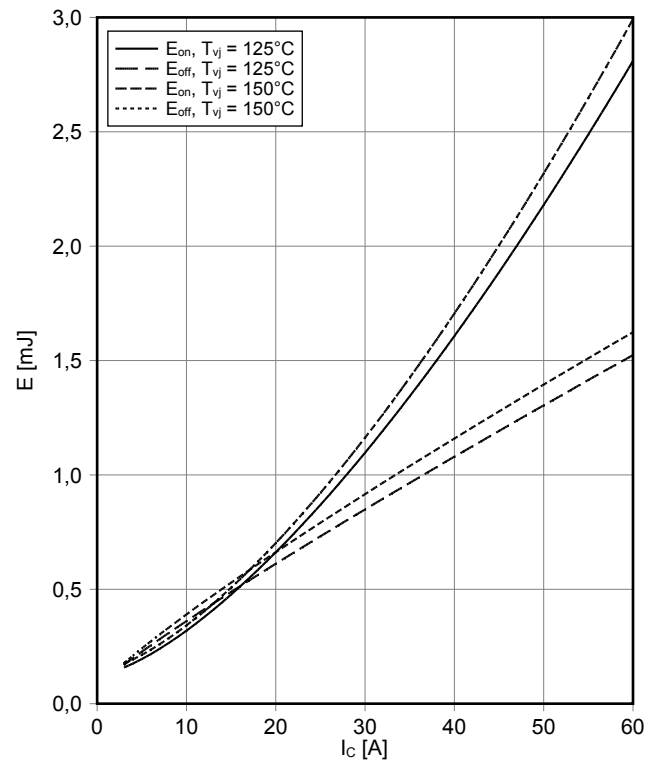
**Übertragungscharakteristik IGBT, Wechselrichter (typisch)**  
**transfer characteristic IGBT, Inverter (typical)**

$I_C = f(V_{GE})$   
 $V_{CE} = 20\text{ V}$



**Schaltverluste IGBT, Wechselrichter (typisch)**  
**switching losses IGBT, Inverter (typical)**

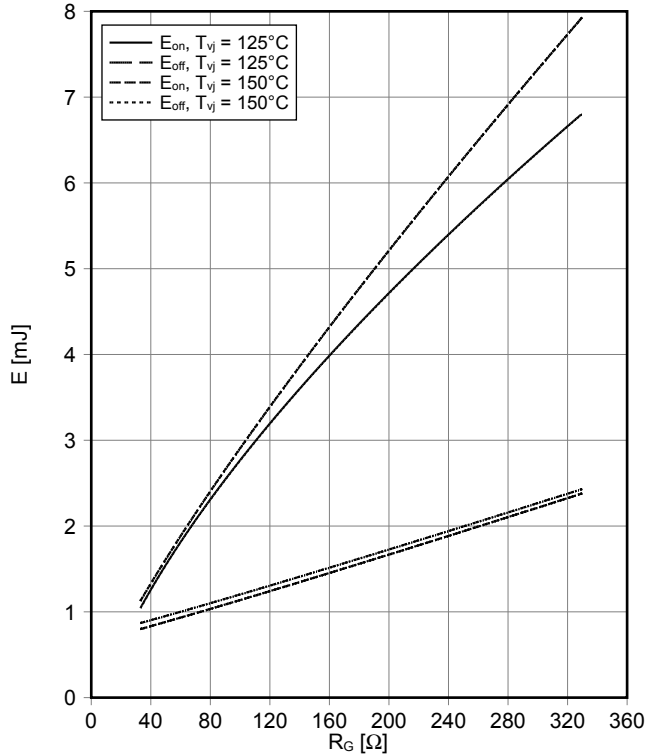
$E_{on} = f(I_C)$ ,  $E_{off} = f(I_C)$   
 $V_{GE} = \pm 15\text{ V}$ ,  $R_{Gon} = 33\ \Omega$ ,  $R_{Goff} = 33\ \Omega$ ,  $V_{CE} = 300\text{ V}$





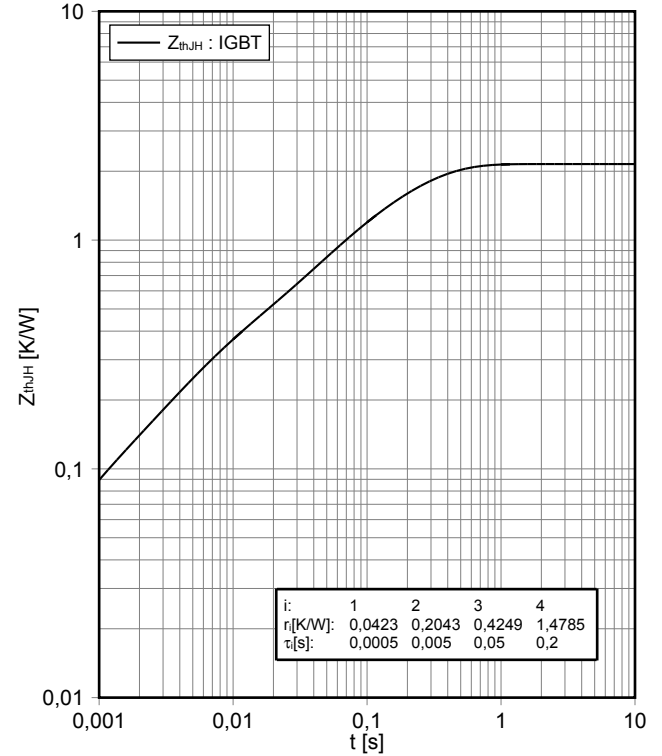
**Schaltverluste IGBT, Wechselrichter (typisch)**  
**switching losses IGBT, Inverter (typical)**

$E_{on} = f(R_G)$ ,  $E_{off} = f(R_G)$   
 $V_{GE} = \pm 15\text{ V}$ ,  $I_C = 30\text{ A}$ ,  $V_{CE} = 300\text{ V}$



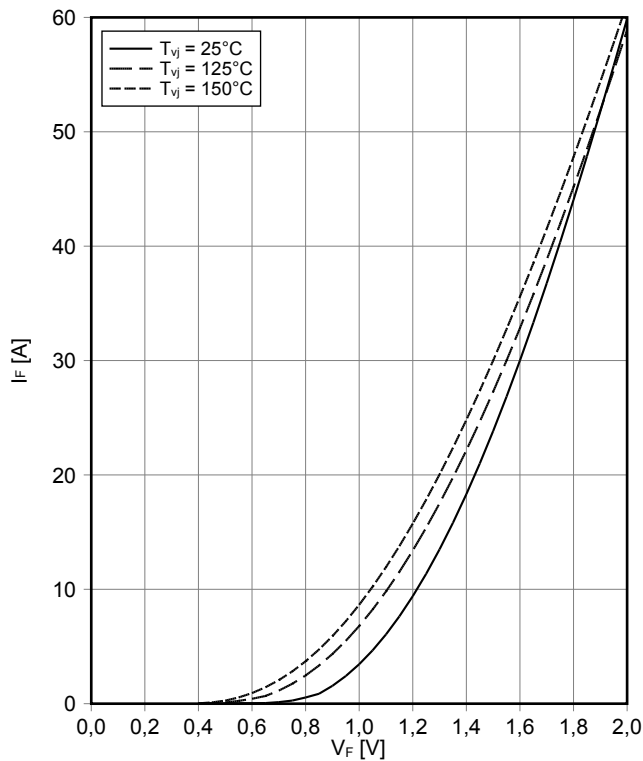
**Transienter Wärmewiderstand IGBT, Wechselrichter**  
**transient thermal impedance IGBT, Inverter**

$Z_{thJH} = f(t)$



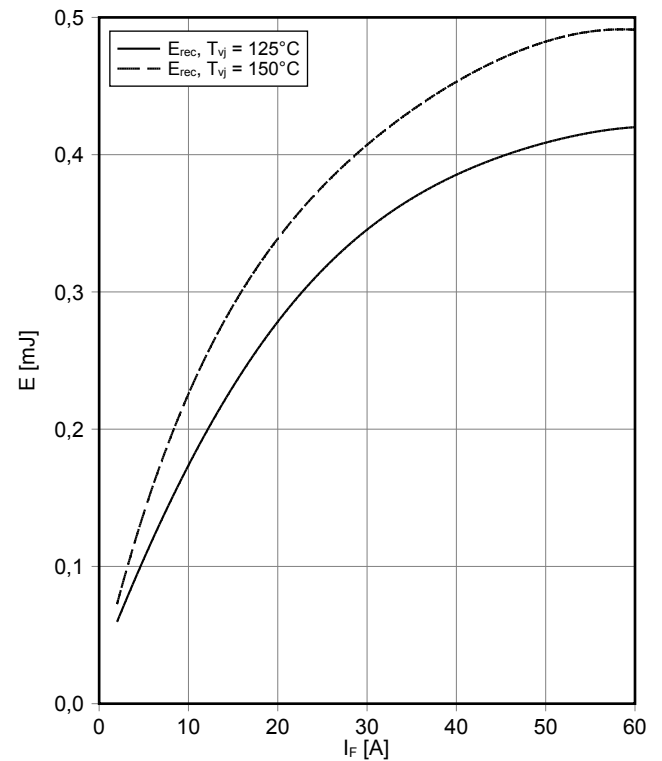
**Durchlasskennlinie der Diode, Wechselrichter (typisch)**  
**forward characteristic of Diode, Inverter (typical)**

$I_F = f(V_F)$



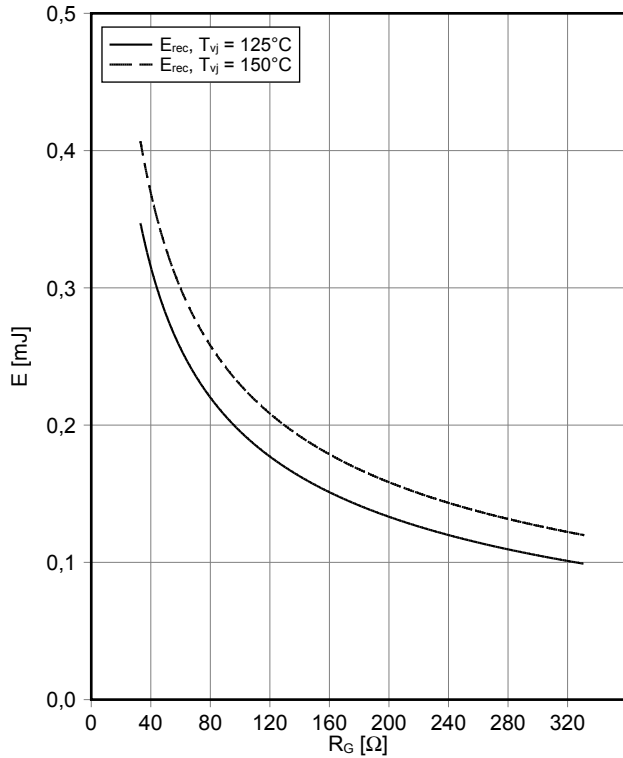
**Schaltverluste Diode, Wechselrichter (typisch)**  
**switching losses Diode, Inverter (typical)**

$E_{rec} = f(I_F)$   
 $R_{Gon} = 33$ ,  $V_{CE} = 300\text{ V}$



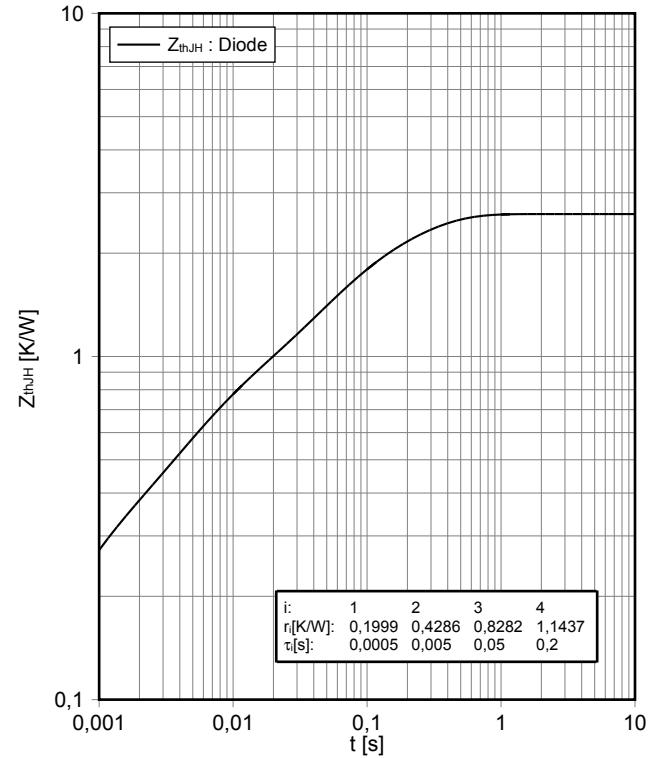
**Schaltverluste Diode, Wechselrichter (typisch)**  
**switching losses Diode, Inverter (typical)**

$E_{rec} = f(R_G)$   
 $I_F = 30\text{ A}, V_{CE} = 300\text{ V}$



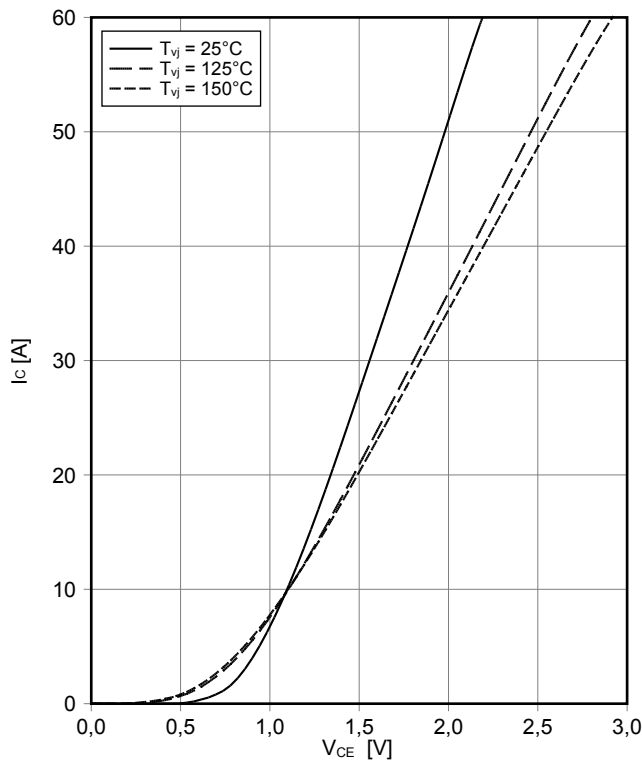
**Transienter Wärmewiderstand Diode, Wechselrichter**  
**transient thermal impedance Diode, Inverter**

$Z_{thJH} = f(t)$



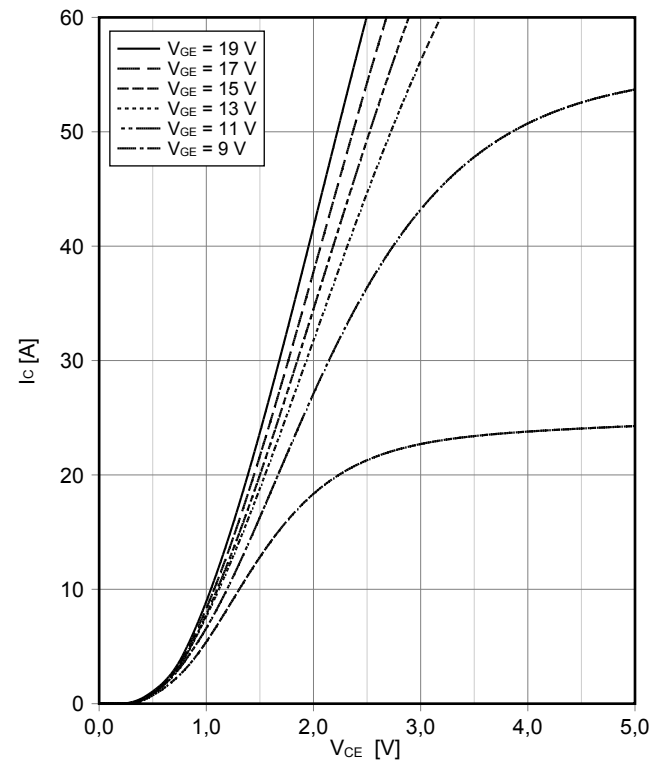
**Ausgangskennlinie IGBT,3-Level (typisch)**  
**output characteristic IGBT,3-Level (typical)**

$I_C = f(V_{CE})$   
 $V_{GE} = 15\text{ V}$



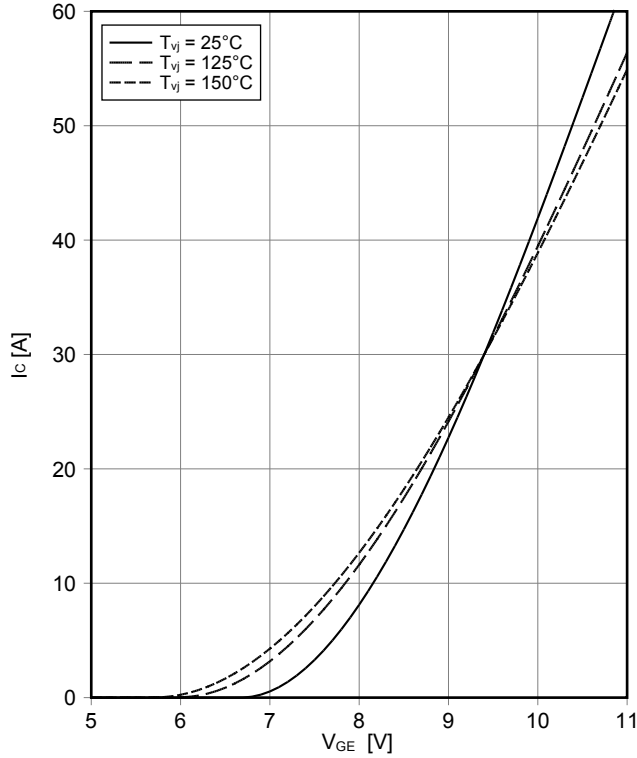
**Ausgangskennlinienfeld IGBT,3-Level (typisch)**  
**output characteristic IGBT,3-Level (typical)**

$I_C = f(V_{CE})$   
 $T_{vj} = 150^\circ\text{C}$



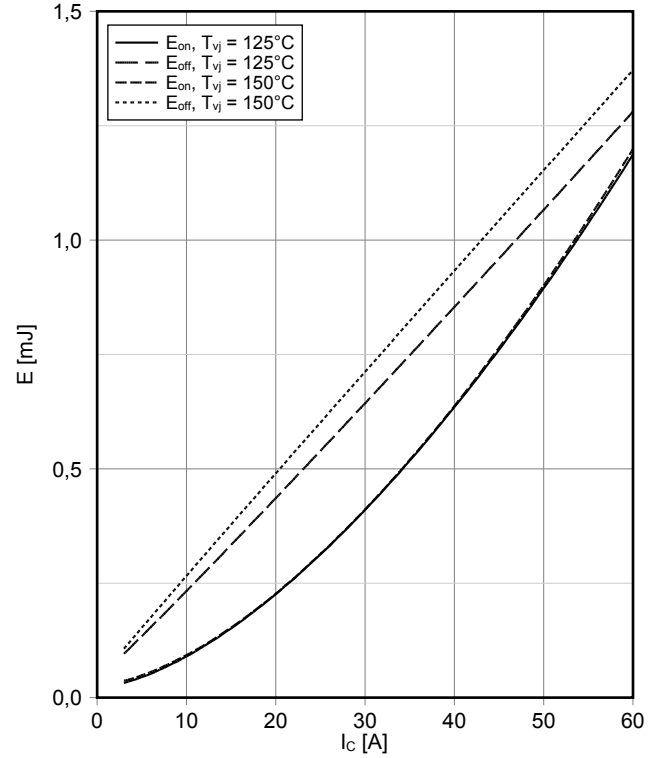
**Übertragungscharakteristik IGBT,3-Level (typisch)**  
**transfer characteristic IGBT,3-Level (typical)**

$I_C = f(V_{GE})$   
 $V_{CE} = 20\text{ V}$



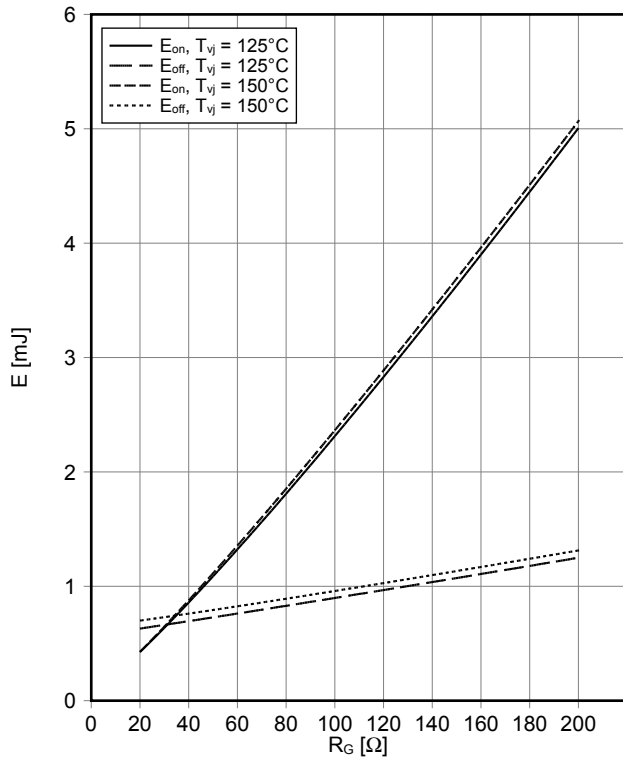
**Schaltverluste IGBT,3-Level (typisch)**  
**switching losses IGBT,3-Level (typical)**

$E_{on} = f(I_C), E_{off} = f(I_C)$   
 $V_{GE} = \pm 15\text{ V}, R_{Gon} = 20\ \Omega, R_{Goff} = 20\ \Omega, V_{CE} = 300\text{ V}$



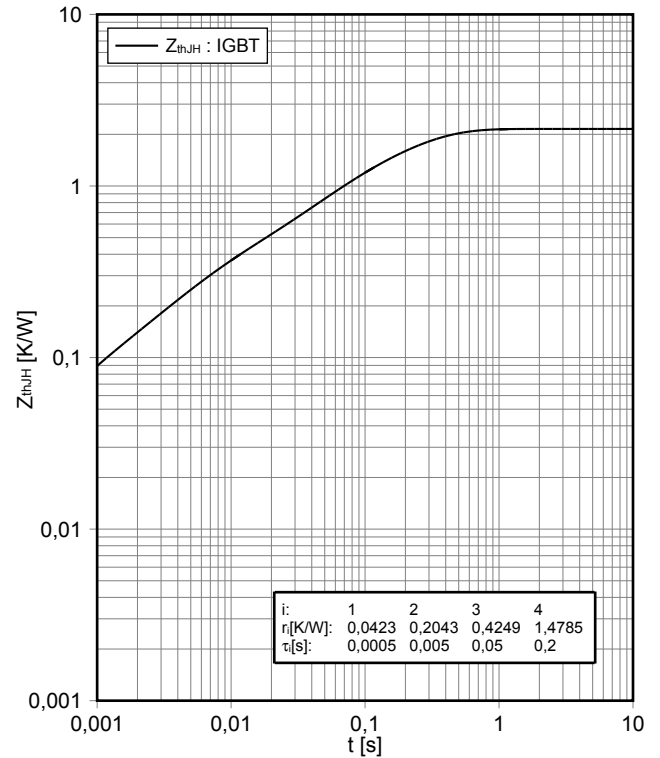
**Schaltverluste IGBT,3-Level (typisch)**  
**switching losses IGBT,3-Level (typical)**

$E_{on} = f(R_G), E_{off} = f(R_G)$   
 $V_{GE} = \pm 15\text{ V}, I_C = 30\text{ A}, V_{CE} = 300\text{ V}$

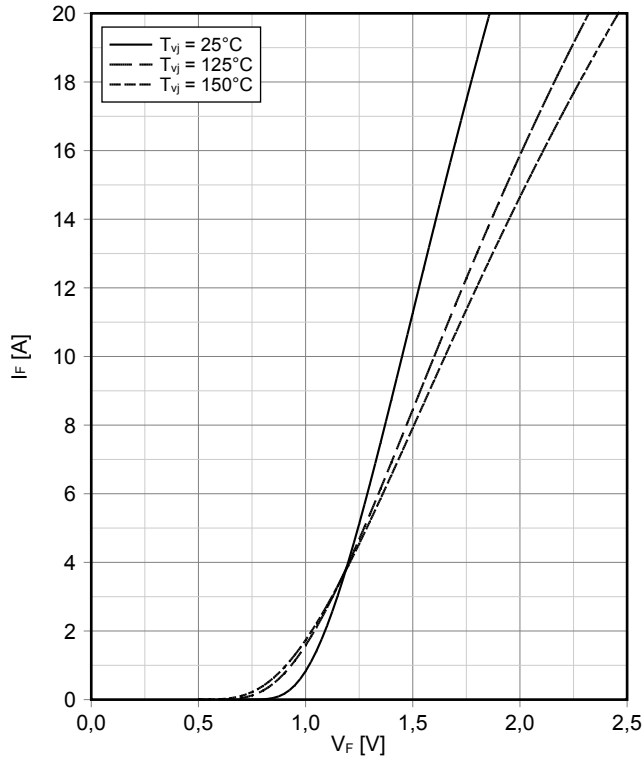


**Transienter Wärmewiderstand IGBT,3-Level**  
**transient thermal impedance IGBT,3-Level**

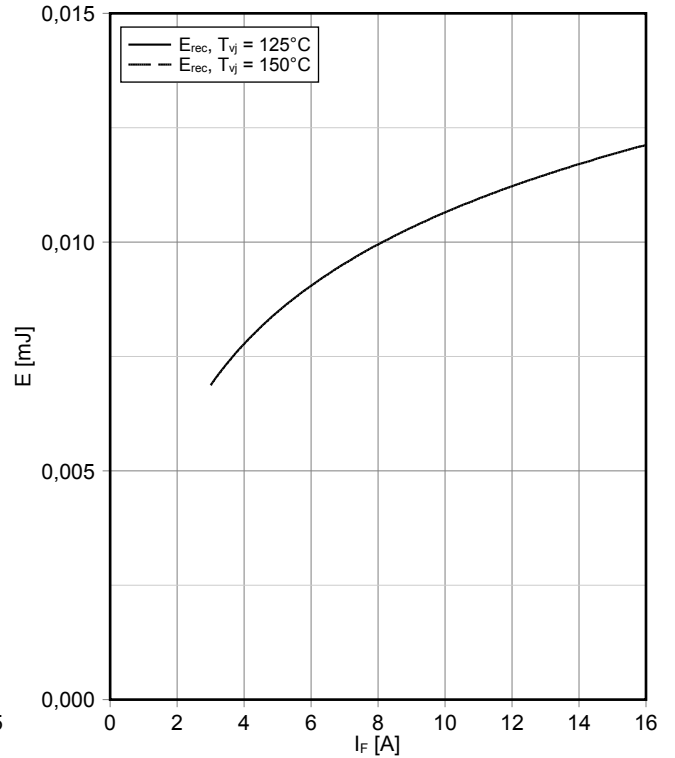
$Z_{thJH} = f(t)$



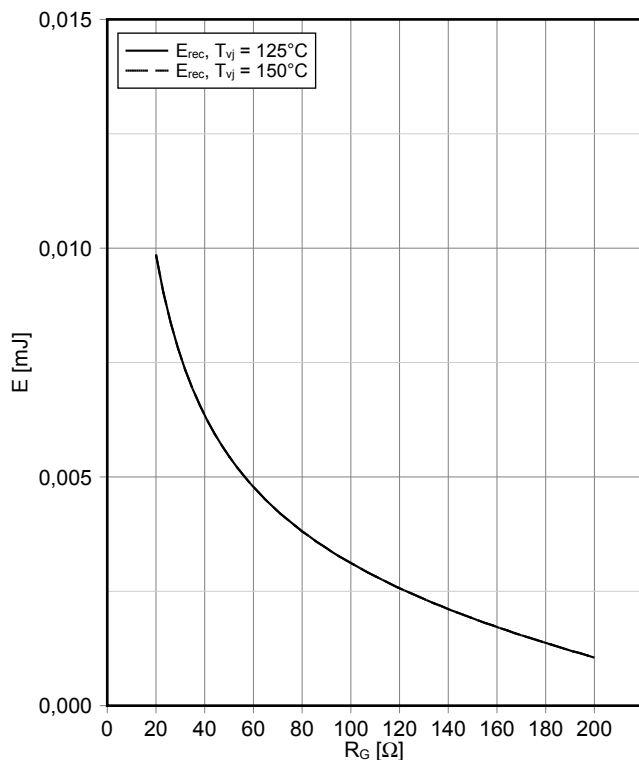
**Durchlasskennlinie der Diode, 3-Level (typisch)**  
**forward characteristic of Diode, 3-Level (typical)**  
 $I_F = f(V_F)$



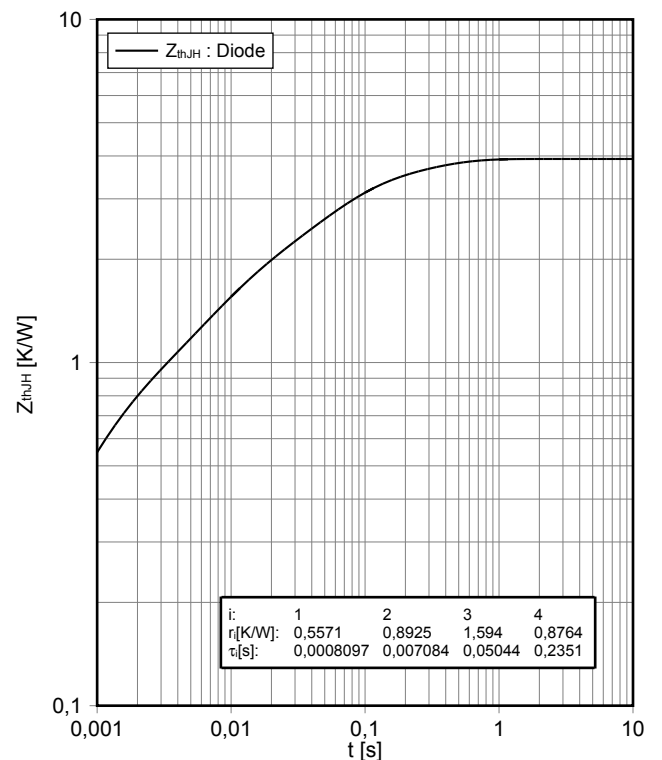
**Schaltverluste Diode, 3-Level (typisch)**  
**switching losses Diode, 3-Level (typical)**  
 $E_{rec} = f(I_F)$   
 $R_{Gon} = 20 \Omega, V_{CE} = 300 \text{ V}$



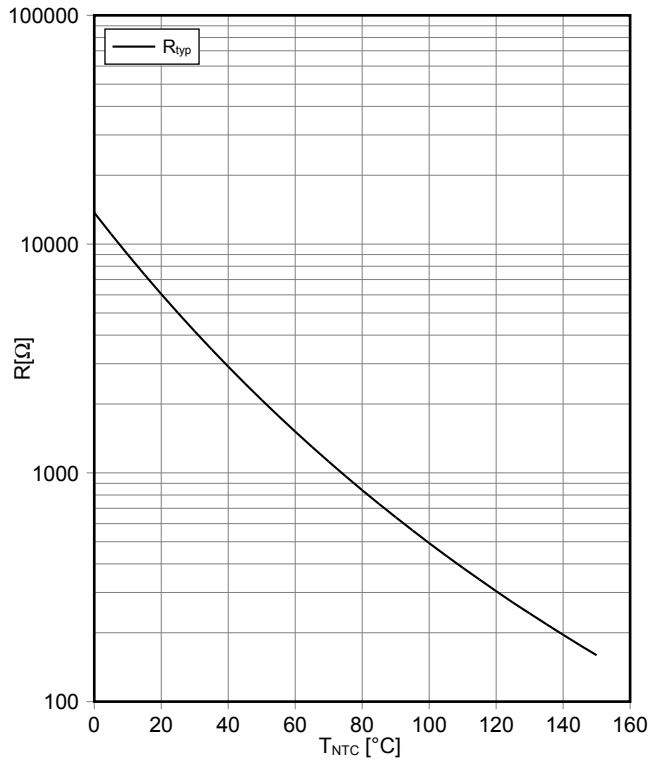
**Schaltverluste Diode, 3-Level (typisch)**  
**switching losses Diode, 3-Level (typical)**  
 $E_{rec} = f(R_G)$   
 $I_F = 10 \text{ A}, V_{CE} = 300 \text{ V}$



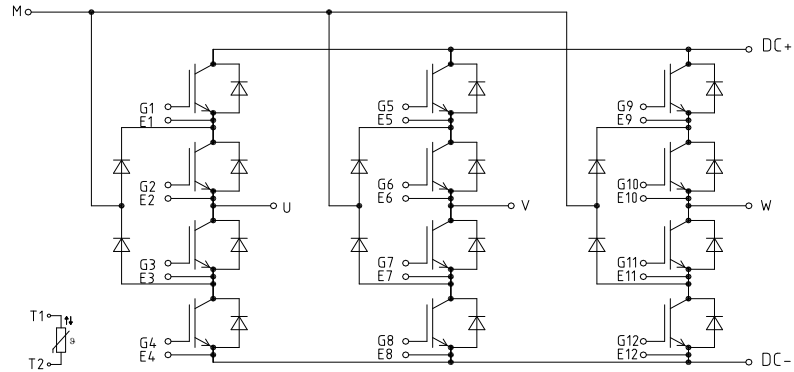
**Transienter Wärmewiderstand Diode, 3-Level**  
**transient thermal impedance Diode, 3-Level**  
 $Z_{thJH} = f(t)$



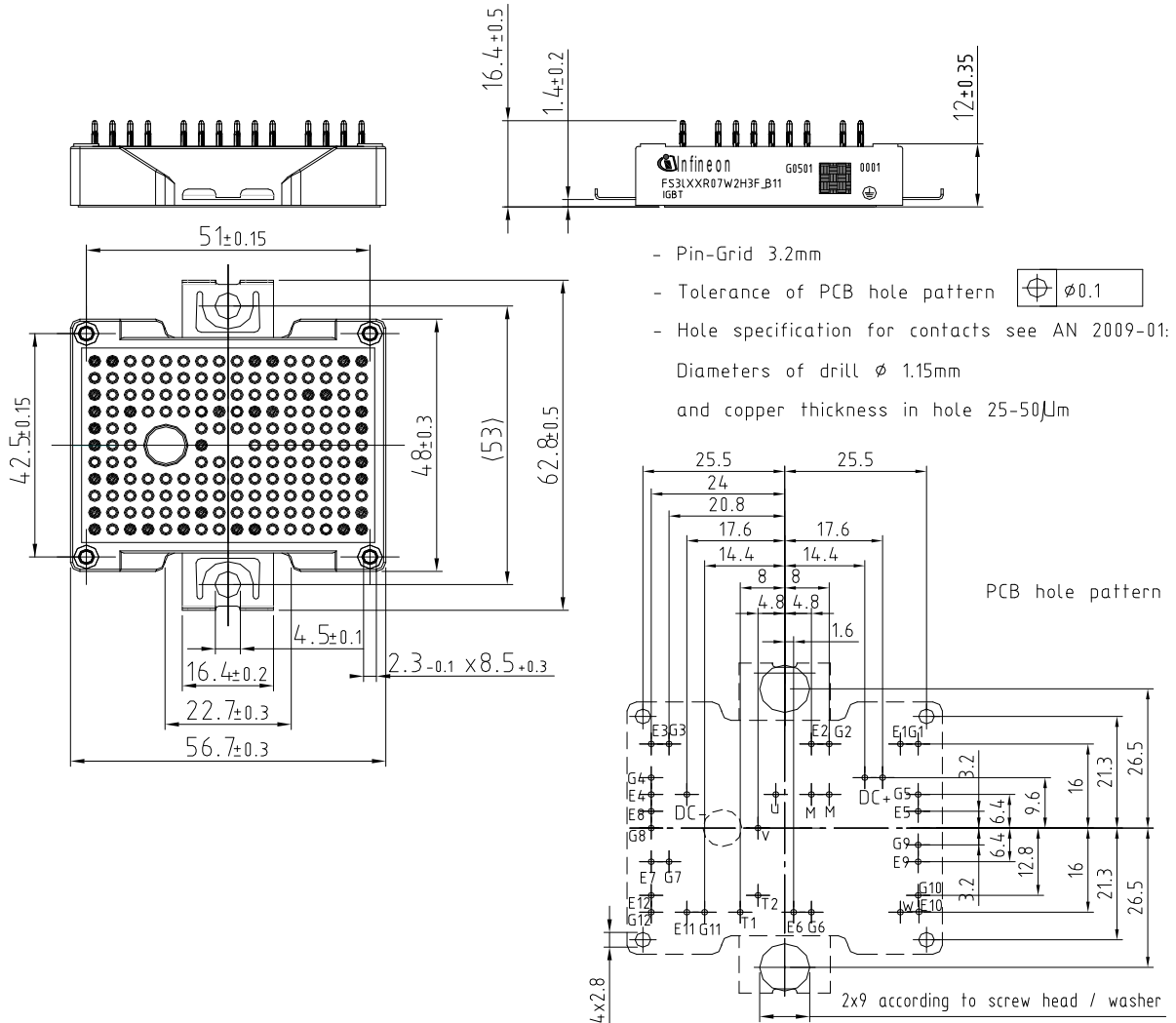
**NTC-Widerstand-Temperaturkennlinie (typisch)**  
**NTC-Thermistor-temperature characteristic (typical)**  
 $R = f(T)$



## Schaltplan / Circuit diagram



## Gehäuseabmessungen / Package outlines



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